

**AMENDMENTS TO THE SPECIFICATION:**

Please REPLACE the first full paragraph on page 15 of the Specification with the following amended paragraph:

In the present preferred embodiment, the ground electrode 12 can be arranged at a location in extremely close proximity to the mounting surface 16. The ground electrode 12 is thus arranged extremely close to the a wiring substrate ~~(not shown in the drawing)~~, e.g., a mother board M, during mounting. In the present preferred embodiment, since no ceramic layer is disposed under the ground electrode 12, the problems of delamination and cracks occurring in ceramic layers under the ground electrode during baking are prevented. Furthermore, since the ground electrode 12 is covered with the resin layer 15, short circuiting between the ground electrode 12 and the electrode of the wiring substrate is prevented even when the ceramic multilayer substrate 101 is mounted on the surface of the wiring substrate ~~(not shown in the drawing)~~, e.g., the mother board M.